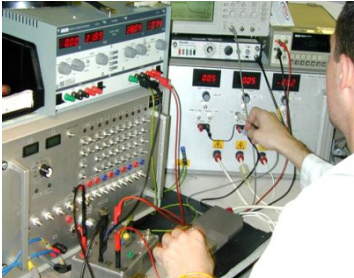


## BUILD-TO-PRINT SERVICES



**APPROVALS**  
BS EN ISO 9001:2000  
MIL 2000 Capabilities

**ENVIRONMENT**  
Static controlled, air  
conditioned



### **SURFACE MOUNT TECHNOLOGY**

Prototype through to volume production, 0402 through to PLCC, QFPs  
Semi-Automatic Screen Printing, IR/Convection Reflow Ovens



### **THROUGH-HOLE TECHNOLOGY**

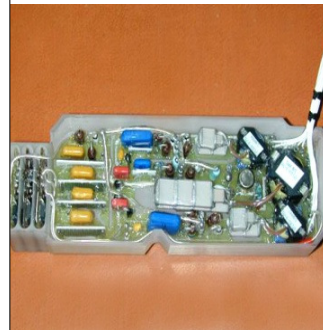
Prototype/Hand Assembly  
Medium batch laser placement  
Tube and Bandolier systems  
Laser placement, crop and bend

### **TECHNIQUES**

Multi-stage aqueous cleaning; Auto lead cropping; Wire wrapping facility; Back plane press fit assembly; Cable loom and cabinet wiring; Through-hole hand soldering; Through-hole wave soldering; Programmable flow-solder oven; Component preparation and encapsulation; Full conformal coating facilities; Vacuum impregnation facilities; Toroidal and RM series winding; Full CNC, milling, turning capabilities; Final assembly and product packaging; Full procurement and materials management; Total turnkey solutions offered

### **TESTING**

Custom ATE Systems  
SMD microscopic  
inspection  
In-circuit emulation; PC  
routines; Burn-in and  
environmental testing  
UV Coating inspection  
facilities; Sinusoidal, bump  
and shock vibration  
Simulated altitude pressure  
chamber; EMC Chamber;  
Combined Thermal and  
Vibration testing



### **RE-WORK**

IC and Connector removal, Hot air SMT Station